Microchip Technology - DSPIC33FJ16MC102T-I/SS Datasheet

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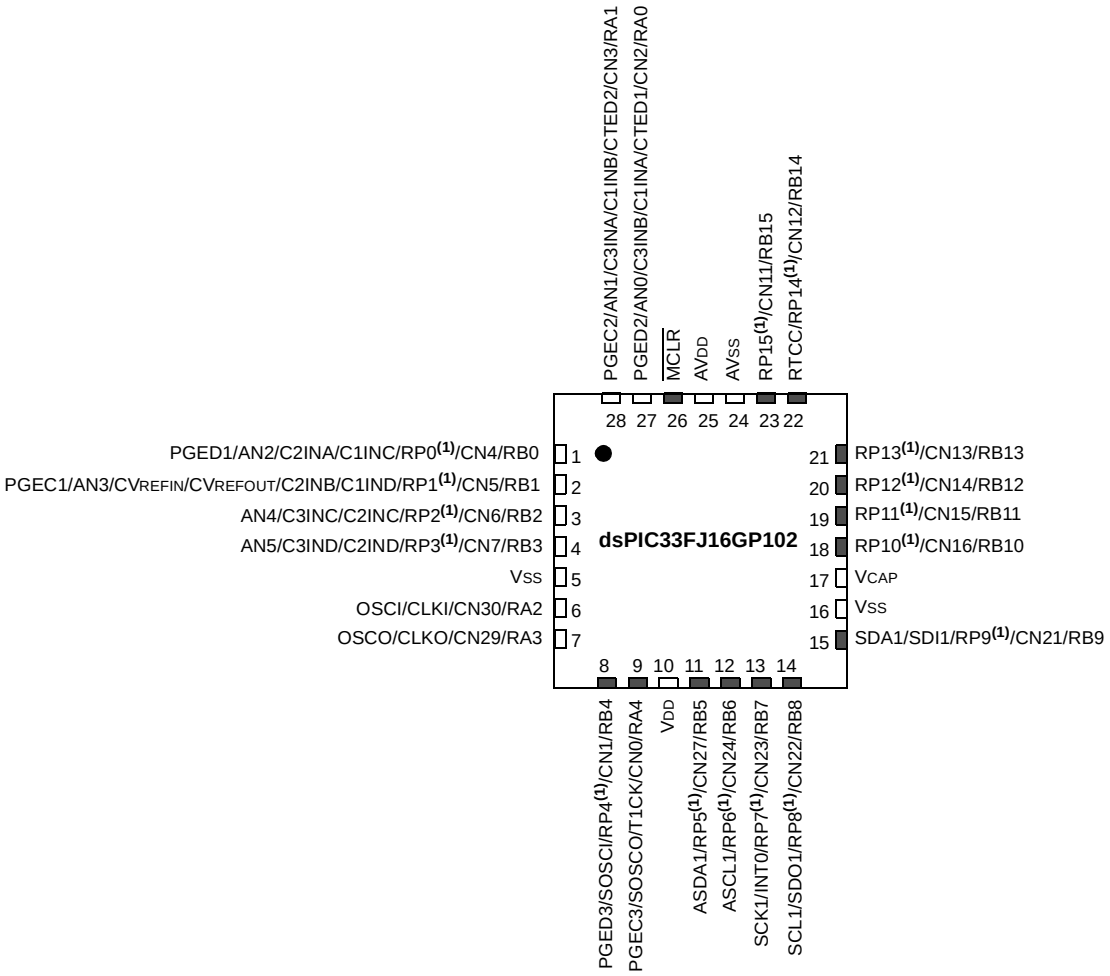
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	16 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj16mc102t-i-ss

Pin Diagrams (Continued)

28-Pin QFN(2)

■ = Pins are up to 5V tolerant



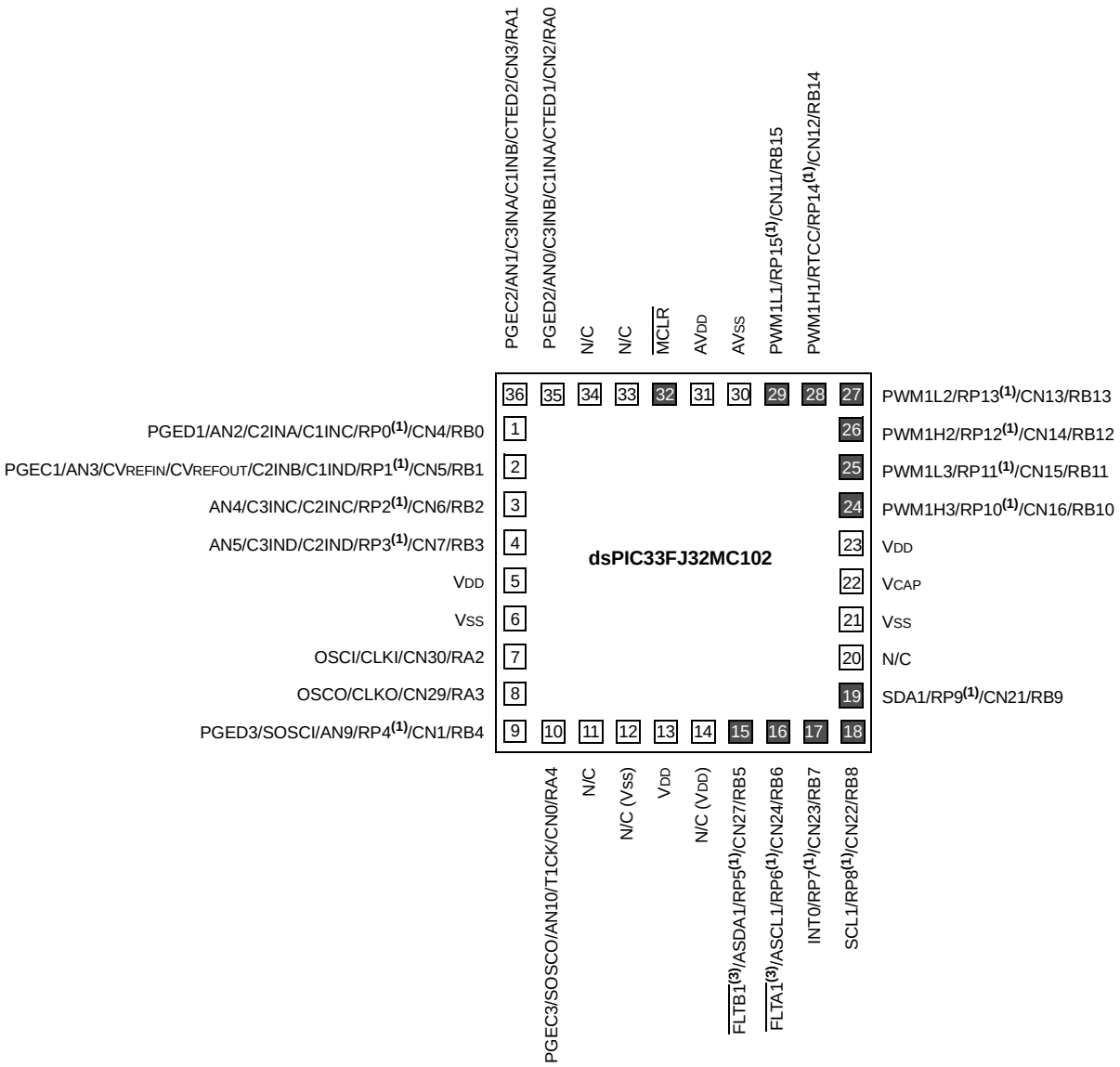
Note 1: The RPn pins can be used by any remappable peripheral. See Table 1 for the list of available peripherals.

2: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

Pin Diagrams (Continued)

36-Pin VTLA(2)

■ = Pins are up to 5V tolerant



Note 1: The RPn pins can be used by any remappable peripheral. See Table 1 for the list of available peripherals.

2: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

3: The PWM Fault pins are enabled and asserted during any Reset event. Refer to **Section 15.2 "PWM Faults"** for more information on the PWM Faults.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes, and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternately, refer to the AC/DC characteristics and timing requirements information in the *"dsPIC33F Flash Programming Specification for Devices with Volatile Configuration Bits"* (DS70659) for information on capacitive loading limits and pin Voltage Input High (V_{IH}) and Voltage Input Low (V_{IL}) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® ICD 3 or MPLAB REAL ICE™.

For more information on ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

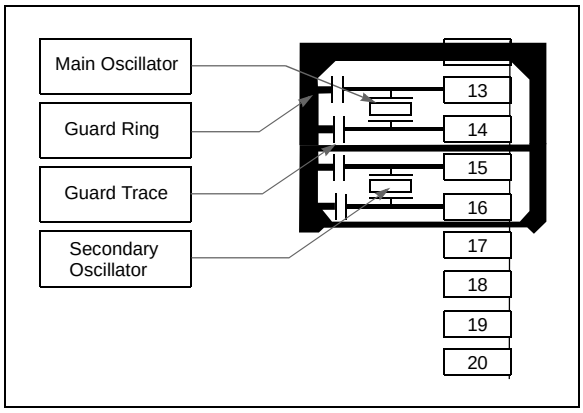
- *"Using MPLAB® ICD 3"* (poster) (DS51765)
- *"MPLAB® ICD 3 Design Advisory"* (DS51764)
- *"MPLAB® REAL ICE™ In-Circuit Debugger User's Guide" (*DS51616)
- *"Using MPLAB® REAL ICE™"* (poster) (DS51749)

2.6 External Oscillator Pins

Many DSCs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator (refer to **Section 8.0 "Oscillator Configuration"** for details).

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is shown in Figure 2-3.

FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT



3.0 CPU

Note 1: This data sheet summarizes the features of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"CPU"** (DS70204) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 CPU module has a 16-bit (data) modified Harvard architecture with an enhanced instruction set, including significant support for DSP. The CPU has a 24-bit instruction word with a variable length opcode field. The Program Counter (PC) is 23 bits wide and addresses up to 4M x 24 bits of user program memory space. The actual amount of program memory implemented varies by device. A single-cycle instruction prefetch mechanism is used to help maintain throughput and provides predictable execution. All instructions execute in a single cycle, with the exception of instructions that change the program flow, the double-word move (`MOV.D`) instruction and the table instructions. Overhead-free program loop constructs are supported using the `DO` and `REPEAT` instructions, both of which are interruptible at any point.

The dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices have sixteen, 16-bit Working registers in the programmer's model. Each of the Working registers can serve as a data, address, or address offset register. The 16th Working register (W15) operates as a Software Stack Pointer (SSP) for interrupts and calls.

There are two classes of instruction in the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices: MCU and DSP. These two instruction classes are seamlessly integrated into a single CPU. The instruction set includes many addressing modes and is designed for optimum C compiler efficiency. For most instructions, dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices are capable of executing a data (or program data) memory read, a Working register (data) read, a data memory write and a program (instruction) memory read per instruction cycle. As a result, three parameter instructions can be supported, allowing A + B = C operations to be executed in a single cycle.

A block diagram of the CPU is shown in Figure 3-1, and the programmer's model for the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 is shown in Figure 3-2.

3.1 Data Addressing Overview

The data space can be addressed as 32K words or 64 Kbytes and is split into two blocks, referred to as X and Y data memory. Each memory block has its own independent Address Generation Unit (AGU). The MCU class of instructions operates solely through the X memory AGU, which accesses the entire memory map as one linear data space. Certain DSP instructions operate through the X and Y AGUs to support dual operand reads, which splits the data address space into two parts. The X and Y data space boundary is device-specific.

Overhead-free circular buffers (Modulo Addressing mode) are supported in both X and Y address spaces. The Modulo Addressing removes the software boundary checking overhead for DSP algorithms. Furthermore, the X AGU circular addressing can be used with any of the MCU class of instructions. The X AGU also supports Bit-Reversed Addressing to greatly simplify input or output data reordering for radix-2 FFT algorithms.

The upper 32 Kbytes of the data space memory map can optionally be mapped into program space at any 16K program word boundary defined by the 8-bit Program Space Visibility Page (PSVPAG) register. The program-to-data-space mapping feature lets any instruction access program space as if it were data space.

3.2 DSP Engine Overview

The DSP engine features a high-speed, 17-bit by 17-bit multiplier, a 40-bit ALU, two 40-bit saturating accumulators and a 40-bit bidirectional barrel shifter. The barrel shifter is capable of shifting a 40-bit value up to 16 bits right or left, in a single cycle. The DSP instructions operate seamlessly with all other instructions and have been designed for optimal real-time performance. The `MAC` instruction and other associated instructions can concurrently fetch two data operands from memory, while multiplying two W registers and accumulating and optionally saturating the result in the same cycle. This instruction functionality requires that the RAM data space be split for these instructions and linear for all others. Data space partitioning is achieved in a transparent and flexible manner through dedicating certain Working registers to each address space.

bit 15							bit 8

W-0	W-0	W-0	W-0	W-0	W-0	W-0	W-0
NVMKEY<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as ‘0’

bit 7-0 **NVMKEY<7:0>:** Key Register bits (write-only)

TABLE 7-1: INTERRUPT VECTORS

Vector Number	Interrupt Request (IRQ) Number	IVT Address	AIVT Address	Interrupt Source
8	0	0x000014	0x000114	INT0 – External Interrupt 0
9	1	0x000016	0x000116	IC1 – Input Capture 1
10	2	0x000018	0x000118	OC1 – Output Compare 1
11	3	0x00001A	0x00011A	T1 – Timer1
12	4	0x00001C	0x00011C	Reserved
13	5	0x00001E	0x00011E	IC2 – Input Capture 2
14	6	0x000020	0x000120	OC2 – Output Compare 2
15	7	0x000022	0x000122	T2 – Timer2
16	8	0x000024	0x000124	T3 – Timer3
17	9	0x000026	0x000126	SPI1E – SPI1 Error
18	10	0x000028	0x000128	SPI1 – SPI1 Transfer Done
19	11	0x00002A	0x00012A	U1RX – UART1 Receiver
20	12	0x00002C	0x00012C	U1TX – UART1 Transmitter
21	13	0x00002E	0x00012E	ADC1 – ADC1
22-23	14-15	0x000030-0x000032	0x000130-0x000132	Reserved
24	16	0x000034	0x000134	SI2C1 – I2C1 Slave Events
25	17	0x000036	0x000136	MI2C1 – I2C1 Master Events
26	18	0x000038	0x000138	CMP – Comparator Interrupt
27	19	0x00003A	0x00013A	Change Notification Interrupt
28	20	0x00003C	0x00013C	INT1 – External Interrupt 1
29-34	21-26	0x00003E-0x000038	0x00013E-0x000138	Reserved
35	27	0x00004A	0x00014A	T4 – Timer4(2)
36	28	0x00004C	0x00014C	T5 – Timer5(2)
37	29	0x00004E	0x00014E	INT2 – External Interrupt 2
38-44	30-36	0x000050-0x00005C	0x000150-0x00015C	Reserved
45	37	0x00005E	0x00015E	IC3 – Input Capture 3
46-64	38-56	0x000060-0x000084	0x000160-0x000184	Reserved
65	57	0x000086	0x000186	PWM1 – PWM1 Period Match(1)
66-69	58-61	0x000088-0x00008E	0x000188-0x00018E	Reserved
70	62	0x000090	0x000190	RTCC – Real-Time Clock and Calendar
71	63	0x000092	0x000192	$\overline{\text{FLTA1}}$ – PWM1 Fault A(1)
72	64	0x000094	0x000194	$\overline{\text{FLTB1}}$ – PWM1 Fault B(3)
73	65	0x000096	0x000196	U1E – UART1 Error
74-84	66-76	0x000098-0x0000AC	0x000198-0x0001AC	Reserved
85	77	0x0000AE	0x0001AE	CTMU – Charge Time Measurement Unit
86-125	78-117	0x0000B0-0x0000FE	0x0001B0-0x0001FE	Reserved

Note 1: This interrupt vector is available in dsPIC33FJ(16/32)MC10X devices only.

2: This interrupt vector is available in dsPIC33FJ32(GP/MC)10X devices only.

3: This interrupt vector is available in dsPIC33FJ(16/32)MC102/104 devices only.

REGISTER 7-1: SR: CPU STATUS REGISTER(1)

R-0	R-0	R/C-0	R/C-0	R-0	R/C-0	R-0	R/W-0
OA	OB	SA	SB	OAB	SAB	DA	DC
bit 15							bit 8

R/W-0(3)	R/W-0(3)	R/W-0(3)	R-0	R/W-0	R/W-0	R/W-0	R/W-0
IPL2(2)	**IPL1(2)**	**IPL0(2)**	RA	N	OV	Z	C
bit 7							bit 0

Legend:	C = Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-5 **IPL<2:0>:** CPU Interrupt Priority Level Status bits(2,3)
111 = CPU Interrupt Priority Level is 7 (15); user interrupts are disabled
110 = CPU Interrupt Priority Level is 6 (14)
101 = CPU Interrupt Priority Level is 5 (13)
100 = CPU Interrupt Priority Level is 4 (12)
011 = CPU Interrupt Priority Level is 3 (11)
010 = CPU Interrupt Priority Level is 2 (10)
001 = CPU Interrupt Priority Level is 1 (9)
000 = CPU Interrupt Priority Level is 0 (8)

Note 1: For complete register details, see Register 3-1.
2: The IPL<2:0> bits are concatenated with the IPL<3> bit (CORCON<3>) to form the CPU Interrupt Priority Level. The value in parentheses indicates the IPL if IPL<3> = 1. User interrupts are disabled when IPL<3> = 1.
3: The IPL<2:0> Status bits are read-only when NSTDIS (INTCON1<15>) = 1.

REGISTER 7-2: CORCON: CORE CONTROL REGISTER(1)

U-0	U-0	U-0	R/W-0	R/W-0	R-0	R-0	R-0
—	—	—	US	EDT	DL2	DL1	DL0
bit 15							bit 8

R/W-0	R/W-0	R/W-1	R/W-0	R/C-0	R/W-0	R/W-0	R/W-0
SATA	SATB	SATDW	ACCSAT	**IPL3(2)**	PSV	RND	IF
bit 7							bit 0

Legend:	C = Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 3 **IPL3:** CPU Interrupt Priority Level Status bit 3(2)
1 = CPU Interrupt Priority Level is greater than 7
0 = CPU Interrupt Priority Level is 7 or less

Note 1: For complete register details, see Register 3-2.
2: The IPL3 bit is concatenated with the IPL<2:0> bits (SR<7:5>) to form the CPU Interrupt Priority Level.

REGISTER 7-7: IFS2: INTERRUPT FLAG STATUS REGISTER 2

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
—	—	IC3IF	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-6 **Unimplemented:** Read as '0'

bit 5 **IC3IF:** Input Capture Channel 3 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 4-0 **Unimplemented:** Read as '0'

REGISTER 7-8: IFS3: INTERRUPT FLAG STATUS REGISTER 3

R/W-0	R/W-0	U-0	U-0	U-0	U-0	R/W-0	U-0
FLTA1IF(1)	RTCIF	—	—	—	—	PWM1IF(1)	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **FLTA1IF:** PWM1 Fault A Interrupt Flag Status bit(1)
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 14 **RTCIF:** RTCC Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 13-10 **Unimplemented:** Read as '0'

bit 9 **PWM1IF:** PWM1 Interrupt Flag Status bit(1)
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 8-0 **Unimplemented:** Read as '0'

Note 1: These bits are available in dsPIC(16/32)MC10X devices only.

REGISTER 7-18: IPC3: INTERRUPT PRIORITY CONTROL REGISTER 3

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	AD1IP2	AD1IP1	AD1IP0	—	U1TXIP2	U1TXIP1	U1TXIP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-7 **Unimplemented:** Read as ‘0’

bit 6-4 **AD1IP<2:0>:** ADC1 Conversion Complete Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as ‘0’

bit 2-0 **U1TXIP<2:0>:** UART1 Transmitter Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

14.2 Output Compare Control Register

REGISTER 14-1: OCxCON: OUTPUT COMPARE x CONTROL REGISTER

U-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
—	—	OCSIDL	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R-0, HC	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	OCFLT	OCTSEL	OCM2	OCM1	OCM0
bit 7							bit 0

Legend:	HC = Hardware Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13 **OCSIDL:** Output Compare x Stop in Idle Mode Control bit
1 = Output Compare x will halt in CPU Idle mode
0 = Output Compare x will continue to operate in CPU Idle mode

bit 12-5 **Unimplemented:** Read as '0'

bit 4 **OCFLT:** PWM Fault Condition Status bit
1 = PWM Fault condition has occurred (cleared in hardware only)
0 = No PWM Fault condition has occurred
(This bit is only used when OCM<2:0> = 111.)

bit 3 **OCTSEL:** Output Compare x Timer Selection bit
1 = Timer3 is the clock source for Output Compare x
0 = Timer2 is the clock source for Output Compare x

bit 2-0 **OCM<2:0>:** Output Compare x Mode Select bits
111 = PWM mode on OCx, Fault pin is enabled
110 = PWM mode on OCx, Fault pin is disabled
101 = Initializes OCx pin low, generates continuous output pulses on OCx pin
100 = Initializes OCx pin low, generates single output pulse on OCx pin
011 = Compare event toggles OCx pin
010 = Initializes OCx pin high, compare event forces OCx pin low
001 = Initializes OCx pin low, compare event forces OCx pin high
000 = Output Compare x channel is disabled

16.0 SERIAL PERIPHERAL INTERFACE (SPI)

Note 1: This data sheet summarizes the features of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Serial Peripheral Interface (SPI)"** (DS70206) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Serial Peripheral Interface (SPI) module is a synchronous serial interface useful for communicating with other peripheral or microcontroller devices. These peripheral devices can be serial EEPROMs, shift registers, display drivers, Analog-to-Digital Converters, etc. The SPI module is compatible with SPI and SIOP from Motorola®.

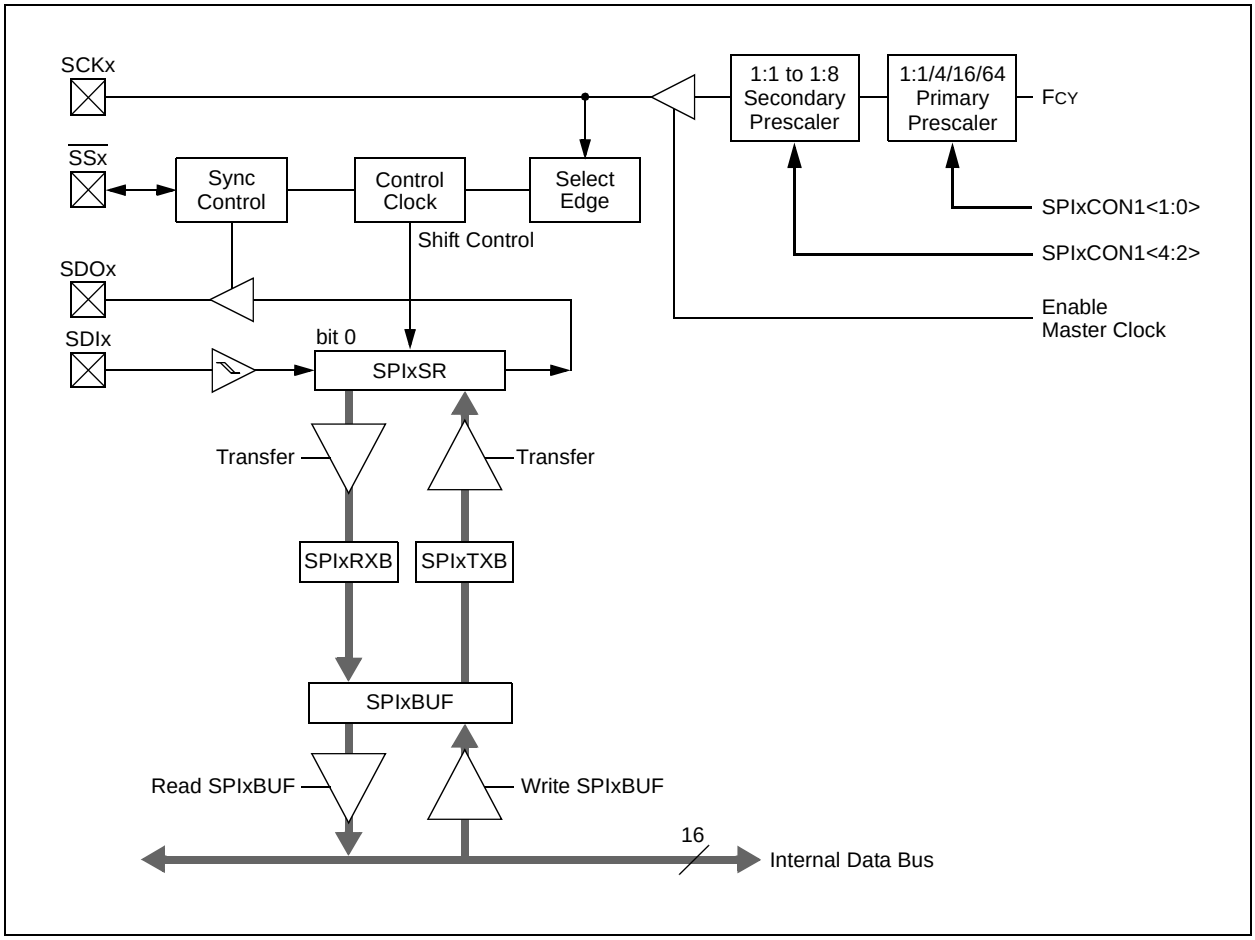
Each SPI module consists of a 16-bit shift register, SPIxSR (where x = 1 or 2), used for shifting data in and out, and a buffer register, SPIxBUF. A control register, SPIxCON, configures the module. Additionally, a status register, SPIxSTAT, indicates status conditions.

The serial interface consists of four pins:

- SDIx (serial data input)
- SDOx (serial data output)
- SCKx (shift clock input or output)
- $\overline{SSx}$ (active-low slave select).

In Master mode operation, SCKx is a clock output. In Slave mode, it is a clock input.

FIGURE 16-1: SPIx MODULE BLOCK DIAGRAM



19.0 10-BIT ANALOG-TO-DIGITAL CONVERTER (ADC)

Note 1: This data sheet summarizes the features of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Analog-to-Digital Converter (ADC)"** (DS70183) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices have up to 14 ADC module input channels.

19.1 Key Features

The 10-bit ADC configuration has the following key features:

- Successive Approximation (SAR) conversion
- Conversion speeds of up to 1.1 Msps
- Up to 14 analog input pins
- Four Sample-and-Hold (S&H) circuits for simultaneous sampling of up to four analog input pins
- Automatic Channel Scan mode
- Selectable conversion trigger source
- Selectable Buffer Fill modes
- Four result alignment options (signed/unsigned, fractional/integer)
- Operation during CPU Sleep and Idle modes
- 16-word conversion result buffer

Depending on the particular device pinout, the ADC can have up to 14 analog input pins.

Block diagrams of the ADC module are shown in Figure 19-1 through Figure 19-3.

19.2 ADC Initialization

To configure the ADC module:

1. Select port pins as analog inputs (AD1PCFGL<15:0>).
2. Select the analog conversion clock to match the desired data rate with the processor clock (ADxCON3<7:0>).
3. Determine how many Sample-and-Hold channels will be used (ADxCON2<9:8>).
4. Select the appropriate sample and conversion sequence (ADxCON1<7:5> and ADxCON3<12:8>).
5. Select the way conversion results are presented in the buffer (ADxCON1<9:8>).
6. Turn on the ADC module (ADxCON1<15>).
7. Configure the ADC interrupt (if required):
   a) Clear the ADxIF bit.
   b) Select the ADC interrupt priority.

TABLE 26-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
Operating Voltage							
DC10	**Supply Voltage(3)**						
	VDD	—	VBOR	—	3.6	V	Industrial and Extended
DC12	VDR	**RAM Data Retention Voltage(2)**	1.8	—	—	V	
DC16	VPOR	**VDD Start Voltage** to Ensure Internal Power-on Reset Signal	—	1.75	VSS	V	
DC17	SVDD	**VDD Rise Rate** to Ensure Internal Power-on Reset Signal	0.024	—	—	V/ms	0-2.4V in 0.1s

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

2: This is the limit to which VDD may be lowered without losing RAM data.

3: Overall functional device operation at VBOR < VDD < VDDMIN is ensured but not characterized. All device analog modules, such as the ADC, etc., will function but with degraded performance below VDDMIN.

TABLE 26-5: ELECTRICAL CHARACTERISTICS: BROWN-OUT RESET (BOR)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min(1)**	**Typ**	**Max**	**Units**	**Conditions**
BO10	VBOR	BOR Event on VDD Transition High-to-Low	2.40	2.48	2.55	V	See **Note 2**

Note 1: Parameters are for design guidance only and are not tested in manufacturing.

2: Overall functional device operation at VBOR < VDD < VDDMIN is ensured but not characterized. All device analog modules, such as the ADC, etc., will function but with degraded performance below VDDMIN.

TABLE 26-7: DC CHARACTERISTICS: IDLE CURRENT (IIDLE) (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.	**Typical(1)**	**Max**	**Units**	**Conditions**		
Idle Current (IIDLE): Core Off, Clock On Base Current(2) – dsPIC33FJ32(GP/MC)10X Devices						
DC40d	0.4	1.0	mA	-40°C	3.3V	LPRC (32.768 kHz)(3)
DC40a	0.4	1.0	mA	+25°C		
DC40b	0.4	1.0	mA	+85°C		
DC40c	0.5	1.0	mA	+125°C		
DC41d	0.5	1.1	mA	-40°C	3.3V	1 MIPS(3)
DC41a	0.5	1.1	mA	+25°C		
DC41b	0.5	1.1	mA	+85°C		
DC41c	0.8	1.1	mA	+125°C		
DC42d	0.9	1.6	mA	-40°C	3.3V	4 MIPS(3)
DC42a	0.9	1.6	mA	+25°C		
DC42b	1.0	1.6	mA	+85°C		
DC42c	1.2	1.6	mA	+125°C		
DC43a	1.6	2.6	mA	+25°C	3.3V	10 MIPS(3)
DC43d	1.6	2.6	mA	-40°C		
DC43b	1.7	2.6	mA	+85°C		
DC43c	2.0	2.6	mA	+125°C		
DC44d	2.4	3.8	mA	-40°C	3.3V	16 MIPS(3)
DC44a	2.4	3.8	mA	+25°C		
DC44b	2.6	3.8	mA	+85°C		
DC44c	2.9	3.8	mA	+125°C		

Note 1: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

2: Base Idle current is measured as follows:

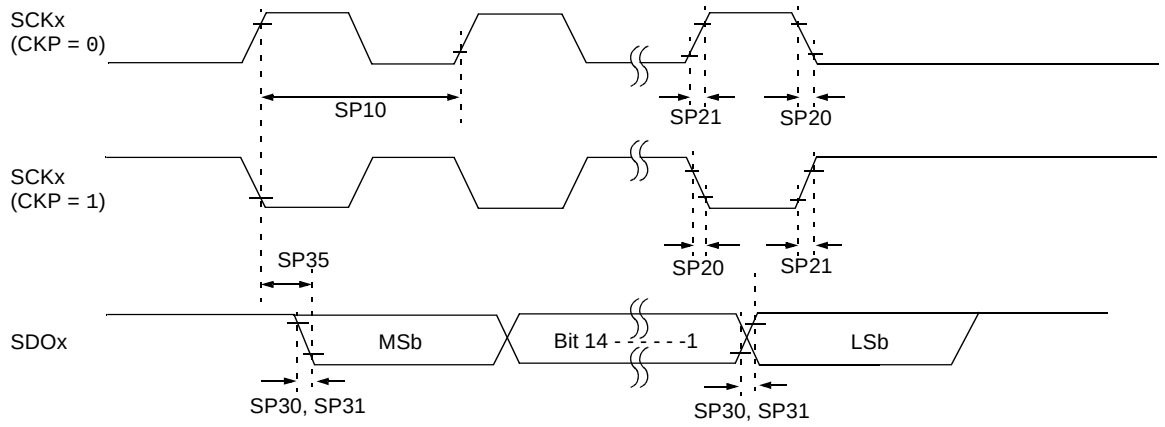
- CPU core is off, oscillator is configured in EC mode, OSC1 is driven with external square wave from rail-to-rail
- CLKO is configured as an I/O input pin in the Configuration Word
- External Secondary Oscillator (SOSC) is disabled (i.e., SOSCO and SOSCI pins are configured as digital I/O inputs)
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{\text{MCLR}}$ = VDD, WDT and FSCM are disabled
- No peripheral modules are operating; however, every peripheral is being clocked (PMDx bits are all zeroed)

3: These parameters are characterized, but not tested in manufacturing.

TABLE 26-37: SPIx MAXIMUM DATA/CLOCK RATE SUMMARY FOR dsPIC33FJ32(GP/MC)10X

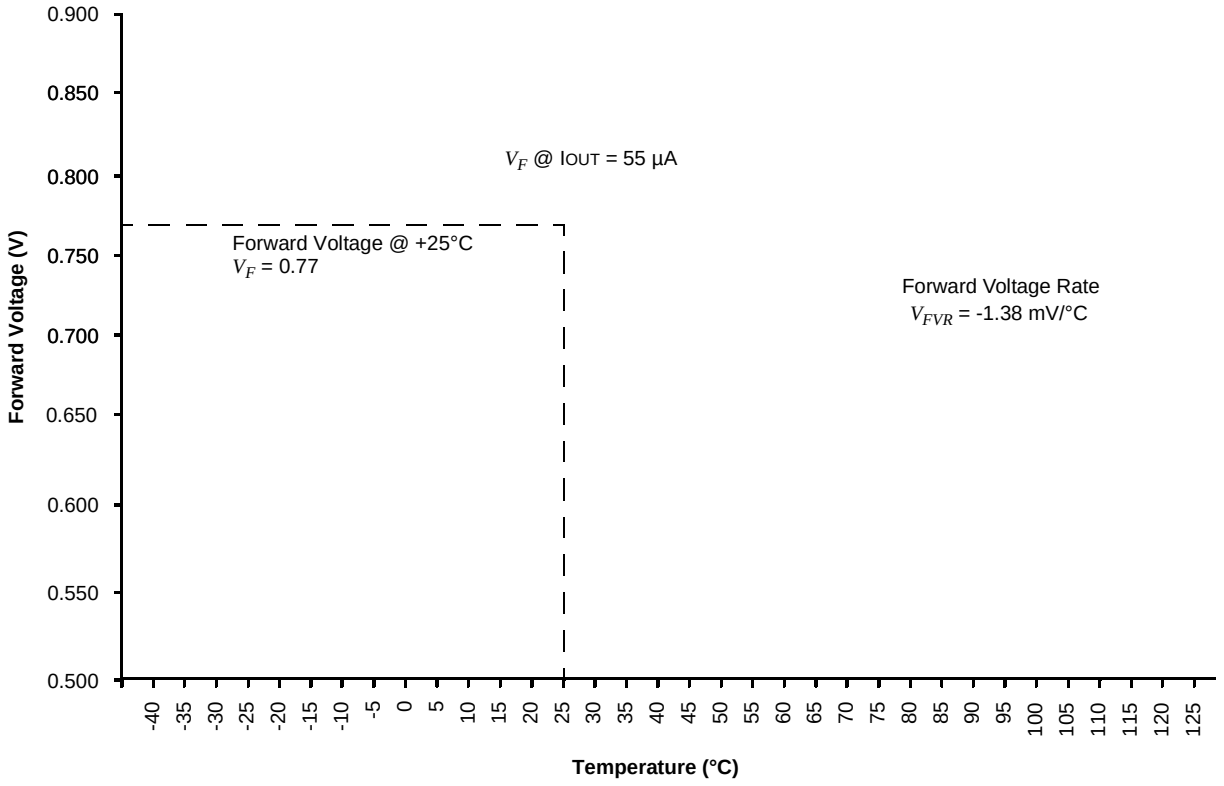
AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Maximum Data Rate	**Master Transmit Only (Half-Duplex)**	**Master Transmit/Receive (Full-Duplex)**	**Slave Transmit/Receive (Full-Duplex)**	**CKE**	**CKP**	**SMP**
15 MHz	Table 26-30	—	—	0,1	0,1	0,1
9 MHz	—	Table 26-31	—	1	0,1	1
9 MHz	—	Table 26-32	—	0	0,1	1
15 MHz	—	—	Table 26-33	1	0	0
11 Mhz	—	—	Table 26-34	1	1	0
15 MHz	—	—	Table 26-35	0	1	0
11 MHz	—	—	Table 26-36	0	0	0

FIGURE 26-19: SPIx MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 0) TIMING CHARACTERISTICS FOR dsPIC33FJ32(GP/MC)10X



Note: Refer to Figure 26-1 for load conditions.

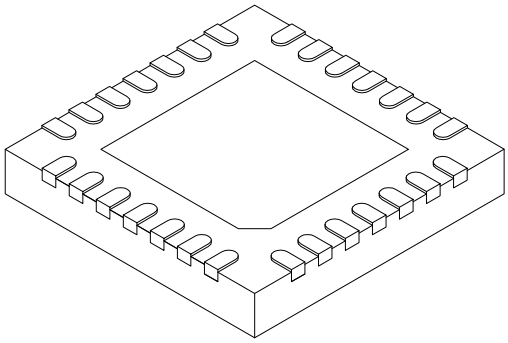
FIGURE 26-33: FORWARD VOLTAGE VERSUS TEMPERATURE



Note: This graph is a statistical summary based on a limited number of samples and this data is characterized but not tested in manufacturing.

28-Lead Plastic Quad Flat, No Lead Package (ML) - 6x6 mm Body [QFN] With 0.55 mm Terminal Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.20 REF	
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	3.65	3.70	4.20
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	3.65	3.70	4.20
Terminal Width	b	0.23	0.30	0.35
Terminal Length	L	0.50	0.55	0.70
Terminal-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-105C Sheet 2 of 2

TABLE A-3: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 26.0 "Electrical Characteristics"	Updated the Absolute Maximum Ratings. Updated TABLE 26-3: Thermal Packaging Characteristics. Updated TABLE 26-6: DC Characteristics: Operating Current (Idd). Updated TABLE 26-7: DC Characteristics: Idle Current (Iidle). Updated TABLE 26-8: DC Characteristics: Power-Down Current (Ipd). Updated TABLE 26-9: DC Characteristics: Doze Current (Idoze). Updated TABLE 26-10: DC Characteristics: I/O Pin Input Specifications. Replaced all SPI specifications and figures (see Table 26-29 through Table 26-44 and Figure 26-11 through Figure 26-26).
Section 28.0 "Packaging Information"	Added the following Package Marking Information and Package Drawings: • 44-Lead TQFP • 44-Lead QFN • 44-Lead VTLA (referred to as TLA in the package drawings)

Revision E (September 2012)

This revision includes updates to the values in **Section 26.0 "Electrical Characteristics"** and updated packaging diagrams in **Section 28.0 "Packaging Information"**. There are minor text edits throughout the document.

Revision F (January 2014)

This revision adds the High-Temperature Electrical Characteristics chapter and updated packaging diagrams in **Section 28.0 "Packaging Information"**. There are minor text edits throughout the document.

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